



PRODUCT DESCRIPTION

At 9 W/m-K thermal conductivity, Tputty™ 910 is at the forefront of thermal performance for a one-part dispensable gap filler. This dispensable gap filler minimizes stress on components during assembly while providing the reliability of a traditional thermal pad. Tputty™ 910 is a soft, compliant, high thermal conductivity dispensable gap filler providing the lowest thermal resistance and highest reliability available.

FEATURES AND BENEFITS

- Thermal Conductivity 9.1W/mK
- Dispensable and Compliant
- Easily reworkable
- Ideal for large gaps
- Meets ROHS and REACH requirements

APPLICATIONS

- Telecom base stations
- Graphic chips
- Microprocessors
- High-power automotive electronic controls

MAIN PROPERTIES

TYPICAL PROPERTIES	VALUE	TEST METHOD
Composition	Ceramic filled dispensable silicone	
Color	Light red	Visual
Flow rate (75cc taper tip, 90psi)	75 g/min	Laird Method
Shelf Life	6 months	Laird Method
Thermal Conductivity	9.1 W/mK	Hot Disk
Density	3.2 g/cc	Helium Pycnometer
Minimum Bond Line Thickness	180 µm	Laird Method
Operating Temperature Range	-40°C to 180°C	
UL Flammability Rating	V-0 (pending)	UL 94
Dielectric Breakdown Voltage	6kV/mm	ASTM D149
Dielectric constant (1MHz)	10	ASTM D150
Volume Resistivity	1.7x10 ¹⁴ Ohm.cm	ASTM D2240
Thermal resistance at 1.5mm, 80°C/40psi	1.76 °C.cm ² /W	ASTM D5470

PACKAGING

PACKAGING SIZE	FILL VOLUME	FILL WEIGHT
30cc syringe	30cc	96g
75cc EFD cartridge	56cc	179g
180cc EFD cartridge	159cc	509g
300cc alu cartridge	300cc	960g
360cc cartridge	326cc	1043g
1 gallon pail	4062cc	13kg

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